

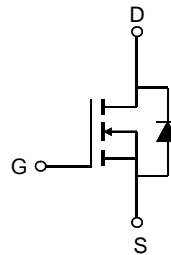
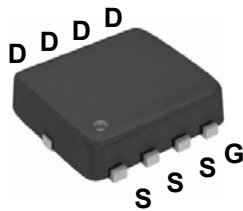
General Description

The HCNR3404 combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is suitable for use in PWM Applications, Load Switch, Power Management and general purpose applications.

Features

V_{DS}	30V
I_D (at $V_{GS}=10V$)	15A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	18m Ω (Typ)
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	24m Ω (Typ)

PDFN3x3



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	30	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current-Continuous	TC=25 $^\circ\text{C}$	I_D	15	A
	TC=100 $^\circ\text{C}$	I_D	9.8	A
Drain Current – Pulsed	I_{DM}	60	A	
Maximum Power Dissipation	P_D	1.45	W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		1.1	$^\circ\text{C}/\text{W}$
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		82	$^\circ\text{C}/\text{W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =4.0A		18	23	mΩ
		V _{GS} =4.5V, I _D =3.0A		24	34	mΩ
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1.0MHz		485		pF
C _{OSS}	Output Capacitance			75		pF
C _{RSS}	Reverse Transfer Capacitance			60		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{GS} =10V V _{DS} =15V R _L =2.6Ω R _{GEN} =3Ω		4.6		nS
t _r	Turn-on Rise Time			2.3		nS
t _{d(off)}	Turn-Off Delay Time			14.6		nS
t _f	Turn-Off Fall Time			3.8		nS
Q _g	Total Gate Charge	V _{DS} =15V, I _D =3A, V _{GS} =4.5V		4.8		nC
Q _{gs}	Gate-Source Charge			0.8		nC
Q _{gd}	Gate-Drain Charge			1.4		nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{SD} =1A		0.72	1.3	V
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		1.5		Ω

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

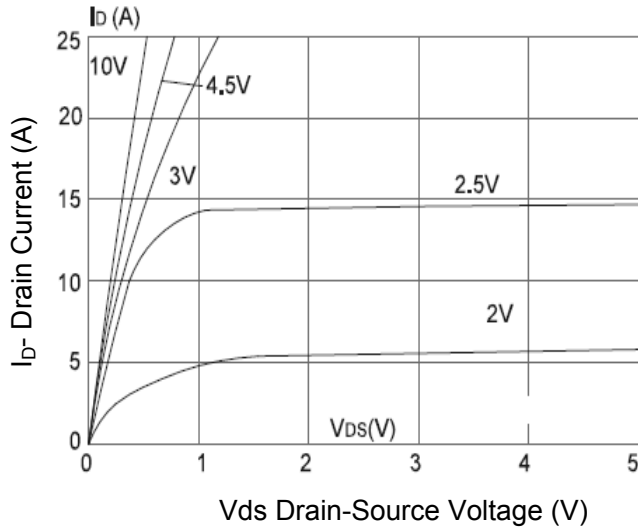


Figure 1 Output Characteristics

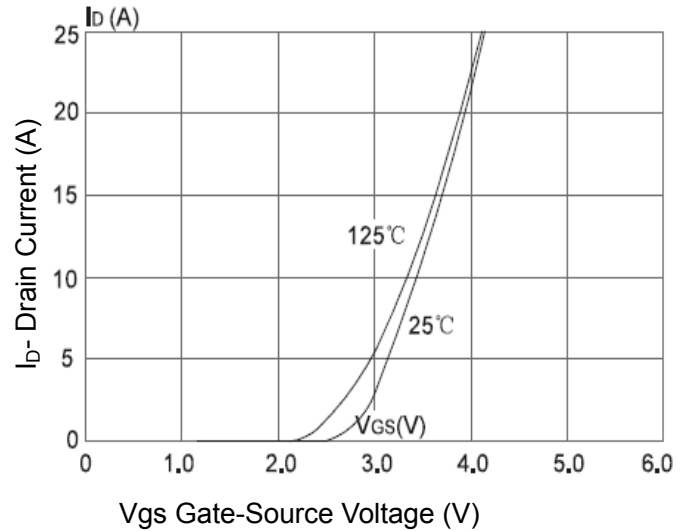


Figure 2 Transfer Characteristics

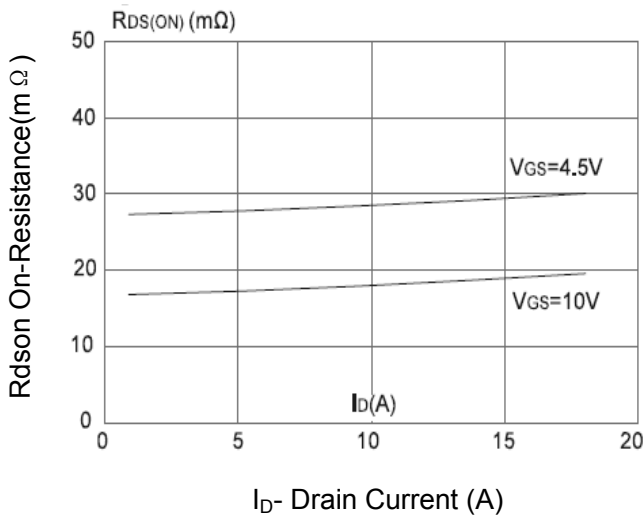


Figure 3 Drain-Source On-Resistance

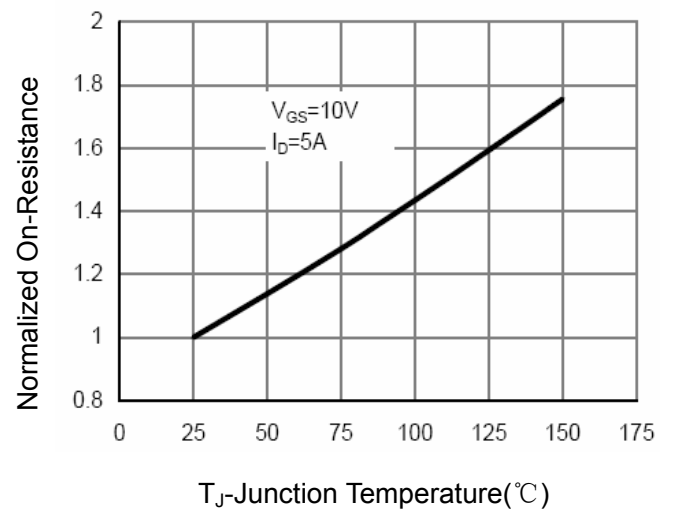


Figure 4 Drain-Source On-Resistance

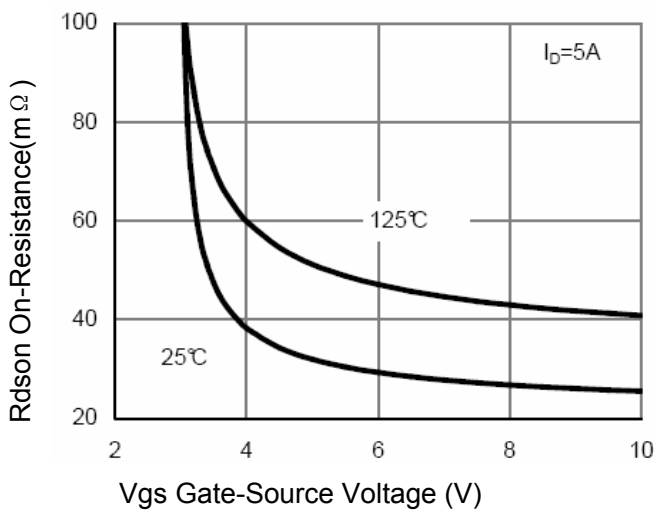


Figure 5 Rdson vs Vgs

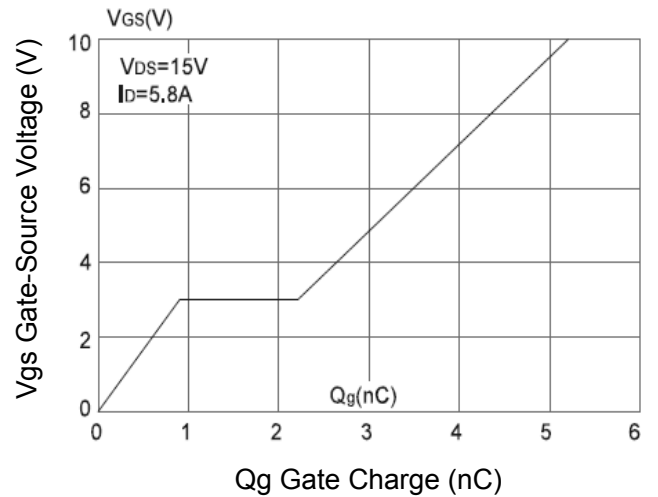


Figure 6 Gate Charge

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

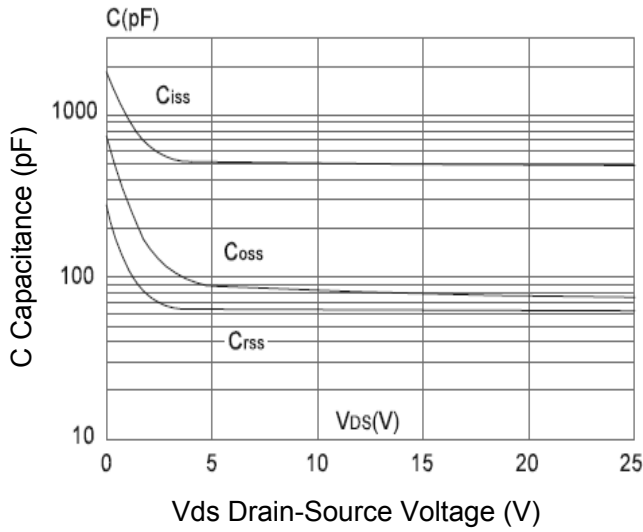


Figure 7 Capacitance vs Vds

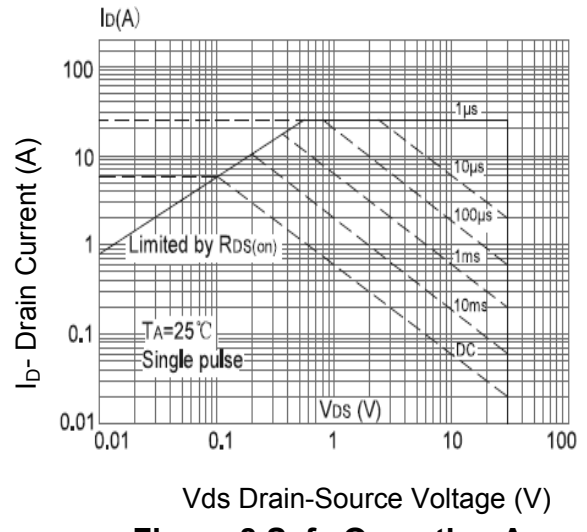


Figure 8 Safe Operation Area

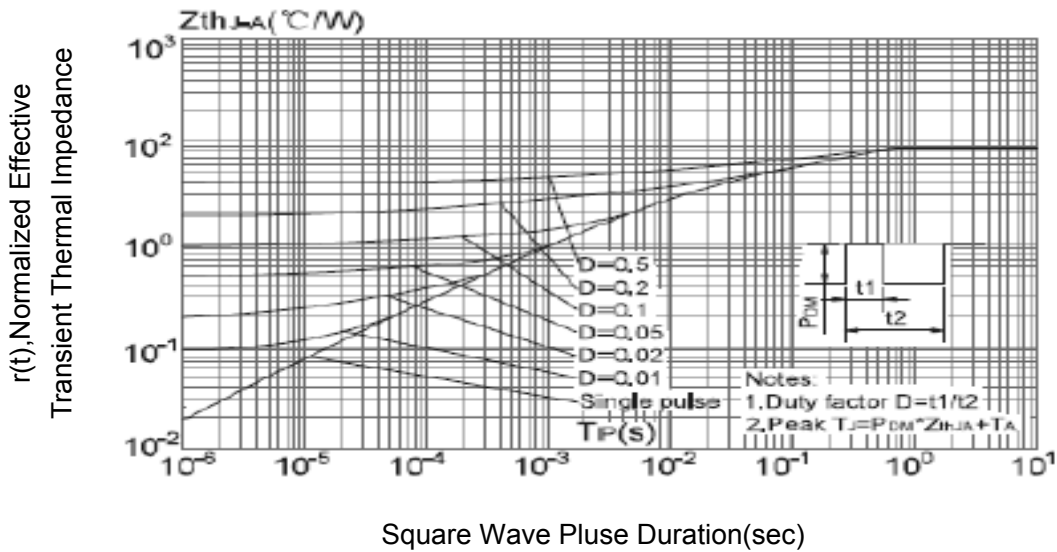
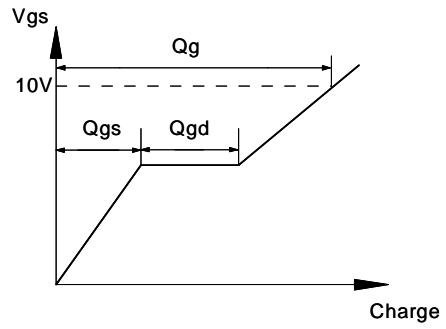
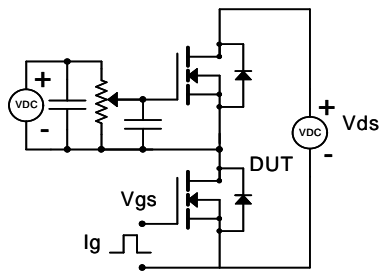
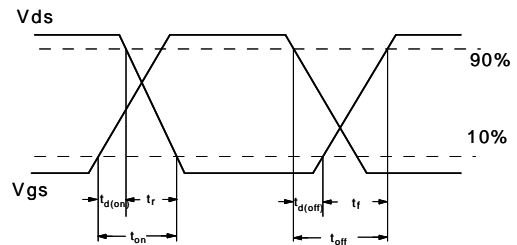
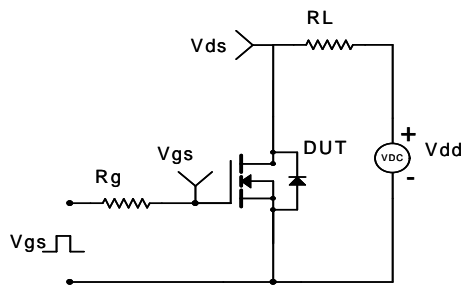


Figure 9 Normalized Maximum Transient Thermal Impedance

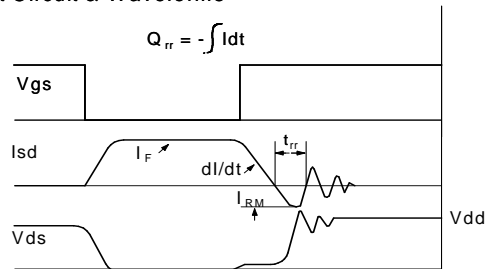
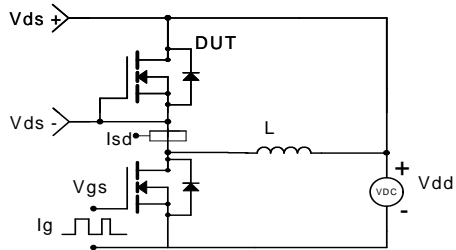
Gate Charge Test Circuit & Waveform



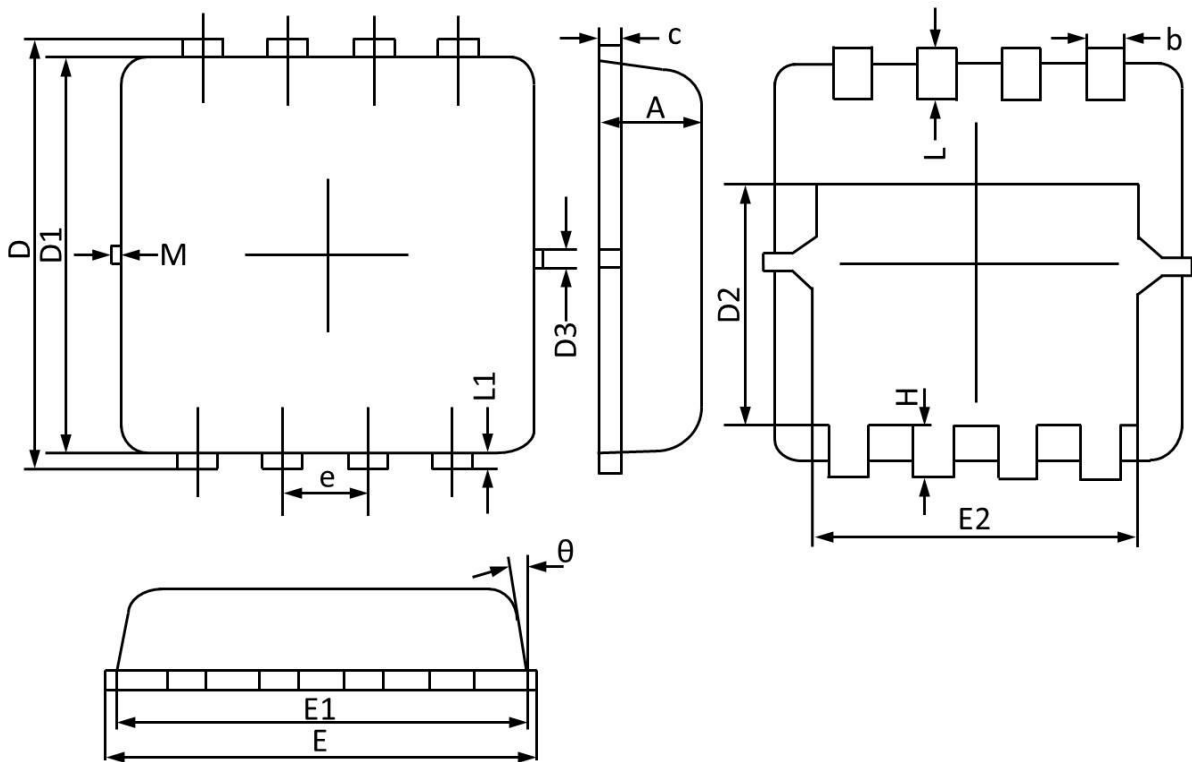
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



PDFN3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
theta	0°	12°	0°	12°
M	0.150 REF		0.006 REF	